


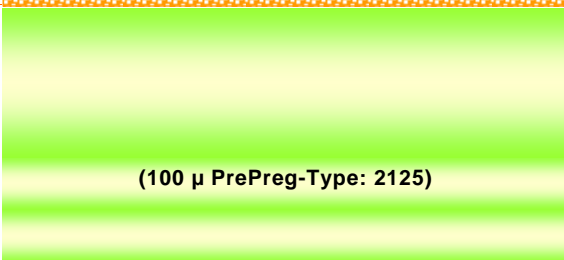








**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**05 298 FR4 55 L108.35\_20.35 P10 S1**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**05\_298\_FR4\_55\_L108.35\_20.35\_p10\_s1**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	55 $\mu$	Copper		A1
	1080 $\mu$	L-FR4		
	100 $\mu$ 100 $\mu$	Prepreg Prepreg	(100 $\mu$ PrePreg-Type: 2125) 	
<b>Layer-2</b>	35 $\mu$	Copper		A2
	200 $\mu$	L-FR4		
<b>Layer-3</b>	35 $\mu$	Copper		A3
	100 $\mu$ 100 $\mu$	Prepreg Prepreg		
<b>Layer-4</b>	35 $\mu$	Copper		
	1080 $\mu$	L-FR4		
<b>Layer-99</b>	55 $\mu$	Copper		B

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